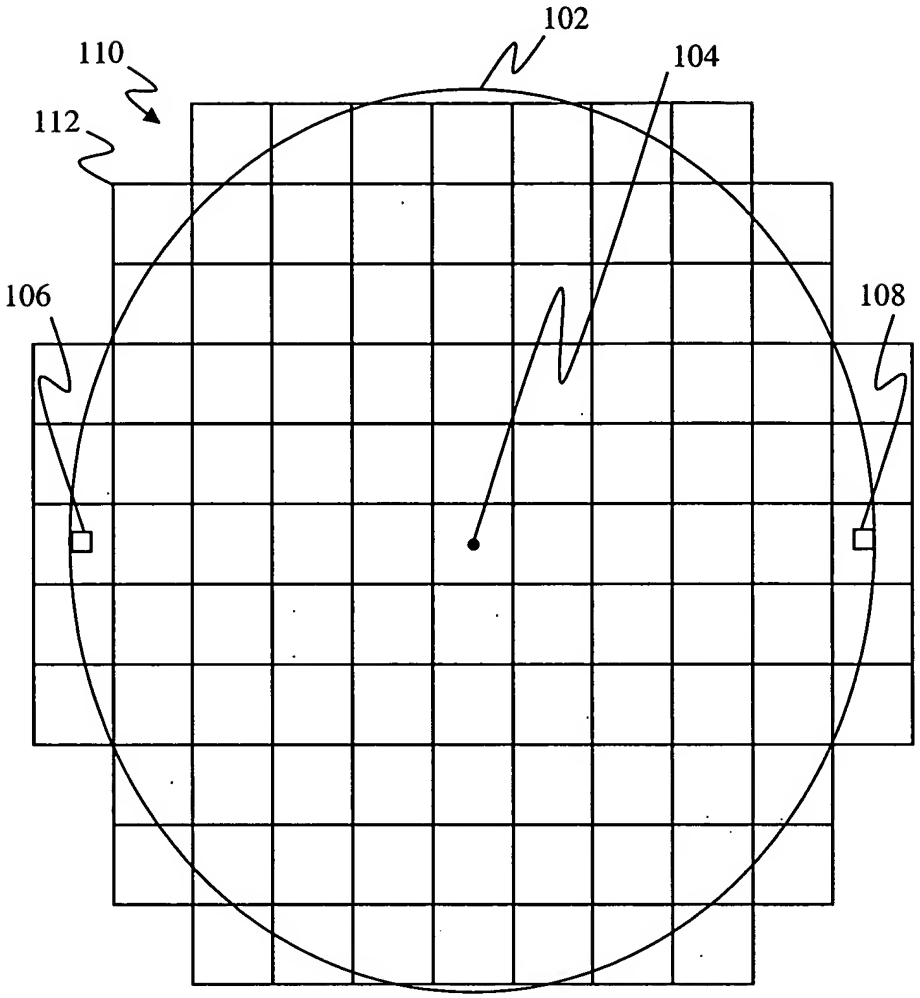

Fig. 1

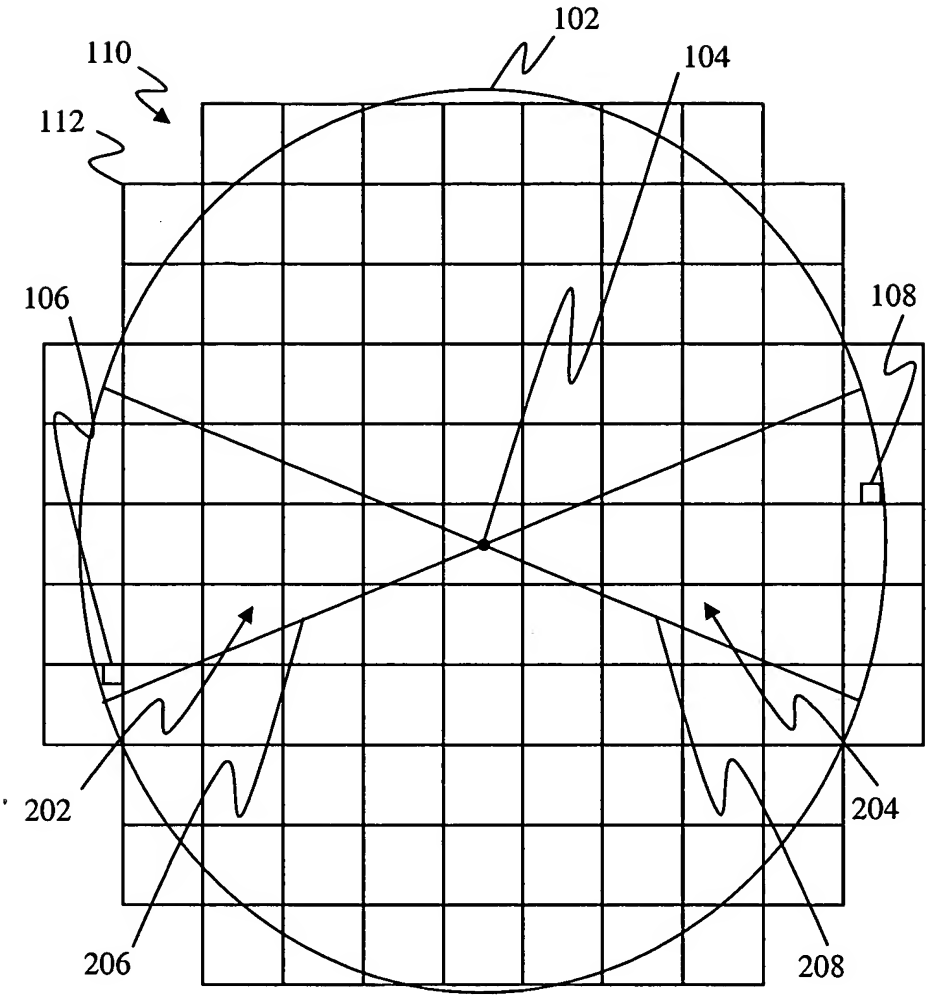

Fig. 2

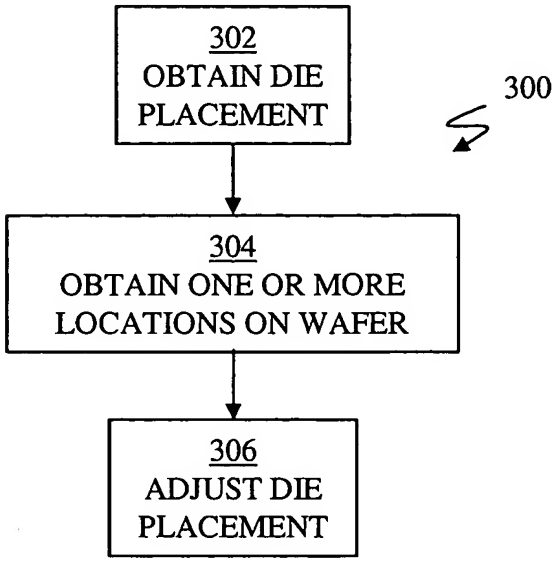
302
OBTAIN DIE PLACEMENT
300
304
OBTAIN ONE OR MORE LOCATIONS ON WAFER
306
ADJUST DIE PLACEMENT

Fig. 3

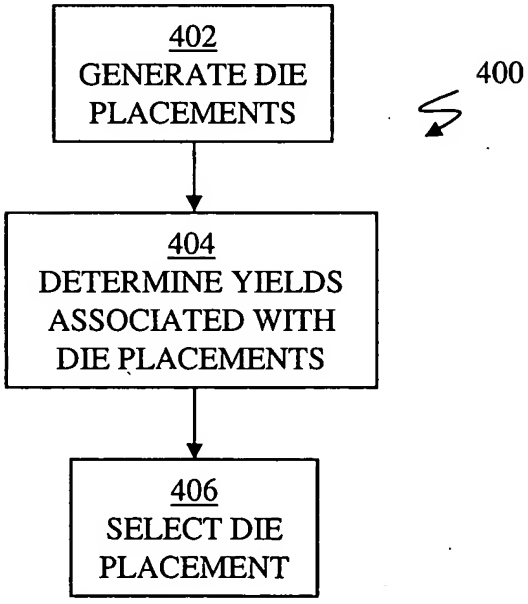
402
GENERATE DIE PLACEMENTS
400
404
DETERMINE YIELDS ASSOCIATED WITH DIE PLACEMENTS
406
SELECT DIE PLACEMENT

Fig. 4

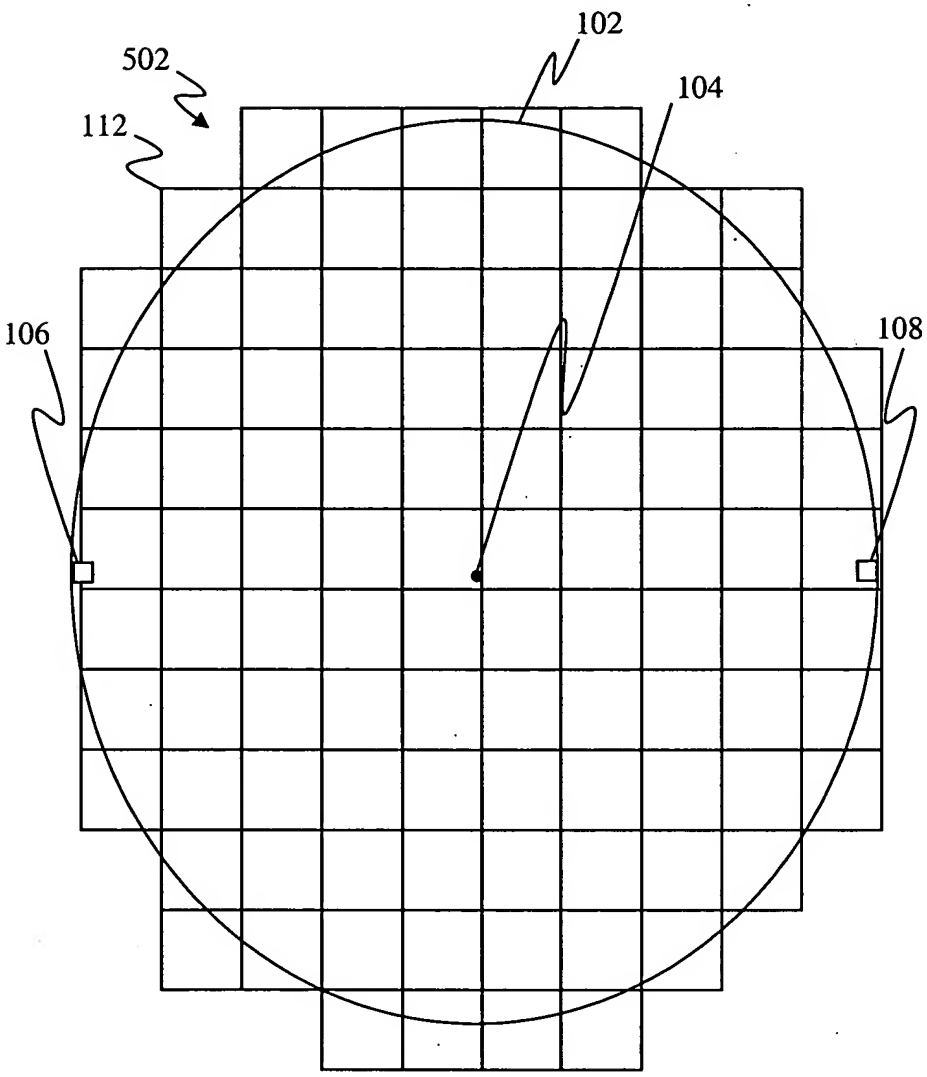

Fig. 5

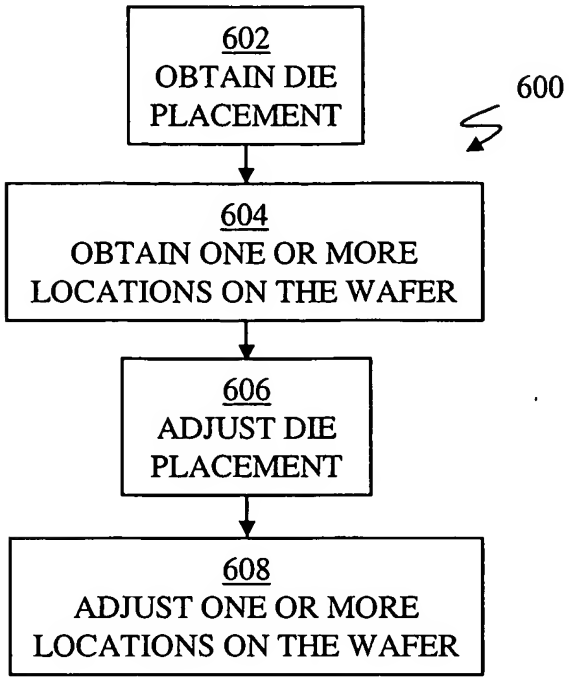
602
OBTAIN DIE PLACEMENT
600
604
OBTAIN ONE OR MORE LOCATIONS ON THE WAFER
606
ADJUST DIE PLACEMENT
608
ADJUST ONE OR MORE LOCATIONS ON THE WAFER

Fig. 6

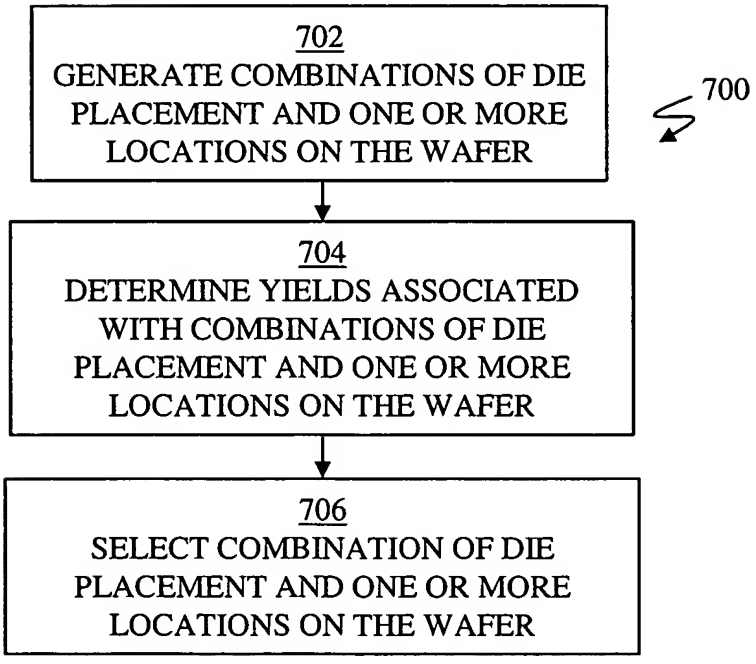
702
GENERATE COMBINATIONS OF DIE PLACEMENT AND ONE OR MORE LOCATIONS ON THE WAFER
700
704
DETERMINE YIELDS ASSOCIATED WITH COMBINATIONS OF DIE PLACEMENT AND ONE OR MORE LOCATIONS ON THE WAFER
706
SELECT COMBINATION OF DIE PLACEMENT AND ONE OR MORE LOCATIONS ON THE WAFER

Fig. 7

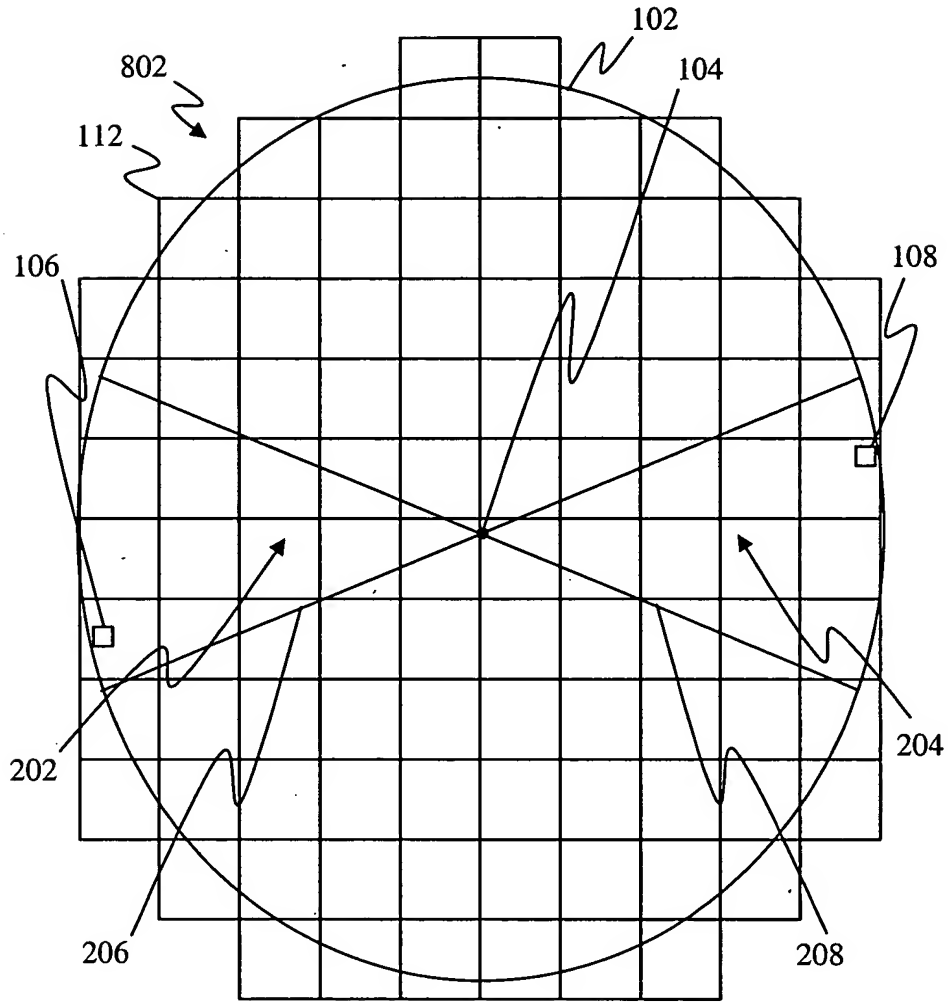

Fig. 8